

Silicon Carbide Schottky Diode

650 V, 4 A

FFSB0465A

Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size and cost.

Features

- Max Junction Temperature 175°C
- Avalanche Rated 25 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Parallelizing
- No Reverse Recovery/No Forward Recovery
- This Device is Pb-Free, Halogen Free/BFR Free and RoHS Compliant

Applications

- General Purpose
- SMPS, Solar Inverter, UPS
- Power Switching Circuits

ABSOLUTE MAXIMUM RATINGS

($T_C = 25^\circ\text{C}$, Unless otherwise specified)

Symbol	Parameter		FFSB0465A	Unit
V_{RRM}	Peak Repetitive Reverse Voltage		650	V
E_{AS}	Single Pulse Avalanche Energy (Note 1)		25	mJ
I_F	Continuous Rectified Forward Current @ $T_C < 160^\circ\text{C}$		4	A
	Continuous Rectified Forward Current @ $T_C < 135^\circ\text{C}$		7.7	
$I_{F, \text{Max}}$	Non-Repetitive Peak Forward Surge Current	$T_C = 25^\circ\text{C}, 10 \mu\text{s}$	360	A
		$T_C = 150^\circ\text{C}, 10 \mu\text{s}$	330	
$I_{F, \text{SM}}$	Non-Repetitive Forward Surge Current	Half-Sine Pulse, $t_p = 8.3 \text{ ms}$	38	A
$I_{F, \text{RM}}$	Repetitive Forward Surge Current	Half-Sine Pulse, $t_p = 8.3 \text{ ms}$	18	A
P_{tot}	Power Dissipation	$T_C = 25^\circ\text{C}$	63	W
		$T_C = 150^\circ\text{C}$	10.5	
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +175	°C

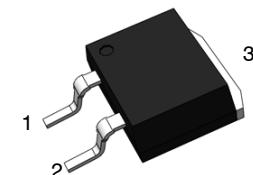
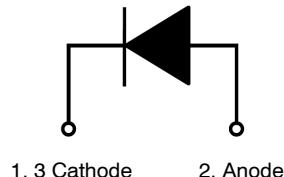
1. E_{AS} of 25 mJ is based on starting $T_J = 25^\circ\text{C}$, $L = 0.5 \text{ mH}$, $I_{AS} = 10 \text{ A}$, $V = 50 \text{ V}$.



ON Semiconductor®

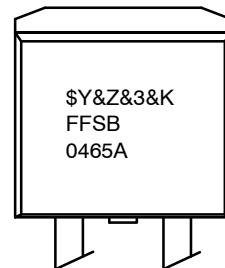
www.onsemi.com

ELECTRICAL CONNECTION



D2PAK2 (TO-263-2L)
CASE 418BK

MARKING DIAGRAM



\$Y = ON Semiconductor Logo
&Z = Assembly Plant Code
&3 = Numeric Date Code
&K = Lot Code
FFSB0465A = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

FFSB0465A

THERMAL CHARACTERISTICS

Symbol	Parameter	Ratings	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	2.38	°C/W

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Mark	Package	Packing Method†	Reel Size	Tape Width	Quantity
FFSB0465A	FFSB0465A	D2PAK	Tape/Reel	N/A	N/A	800 Units

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Forward Voltage	$I_F = 4 \text{ A}, T_C = 25^\circ\text{C}$	–	1.50	1.75	V
		$I_F = 4 \text{ A}, T_C = 125^\circ\text{C}$	–	1.6	2.0	
		$I_F = 4 \text{ A}, T_C = 175^\circ\text{C}$	–	1.72	2.4	
I_R	Reverse Current	$V_R = 650 \text{ V}, T_C = 25^\circ\text{C}$	–	–	200	μA
		$V_R = 650 \text{ V}, T_C = 125^\circ\text{C}$	–	–	400	
		$V_R = 650 \text{ V}, T_C = 175^\circ\text{C}$	–	–	600	
Q_C	Total Capacitive Charge	$V = 400 \text{ V}$	–	16	–	nC
C	Total Capacitance	$V_R = 1 \text{ V}, f = 100 \text{ kHz}$	–	258	–	pF
		$V_R = 200 \text{ V}, f = 100 \text{ kHz}$	–	29	–	
		$V_R = 400 \text{ V}, f = 100 \text{ kHz}$	–	21	–	

TYPICAL CHARACTERISTICS $T_J = 25^\circ\text{C}$ Unless Otherwise Noted

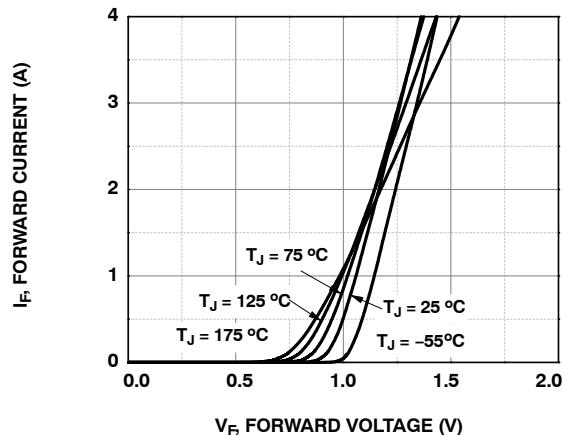


Figure 1. Forward Characteristics

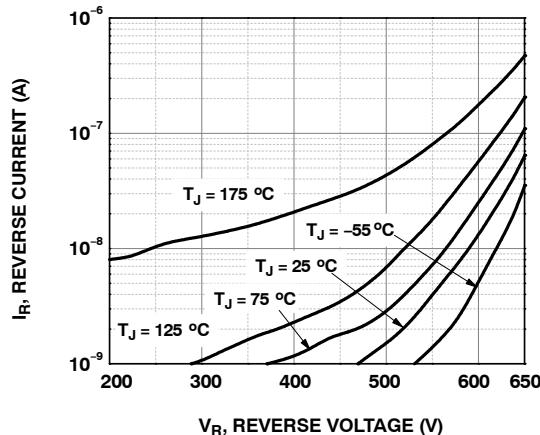


Figure 2. Reverse Characteristics

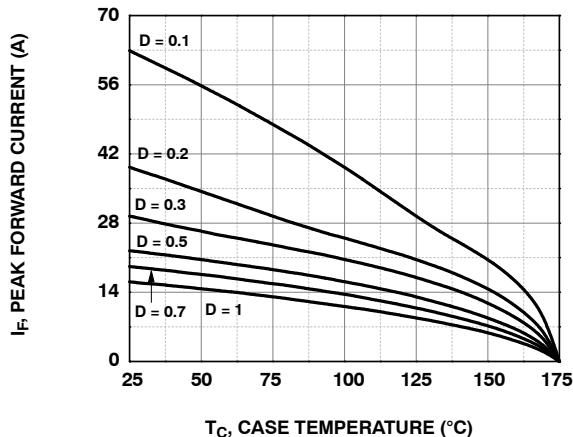


Figure 3. Current Derating

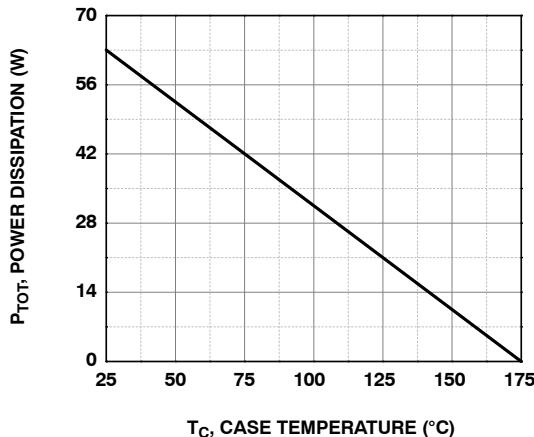


Figure 4. Power Derating

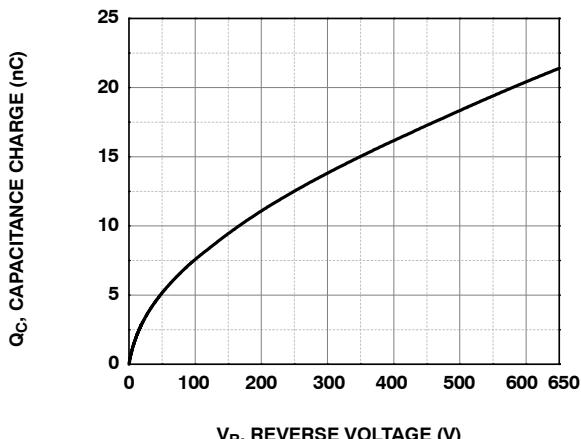


Figure 5. Capacitance Charge vs. Reverse Voltage

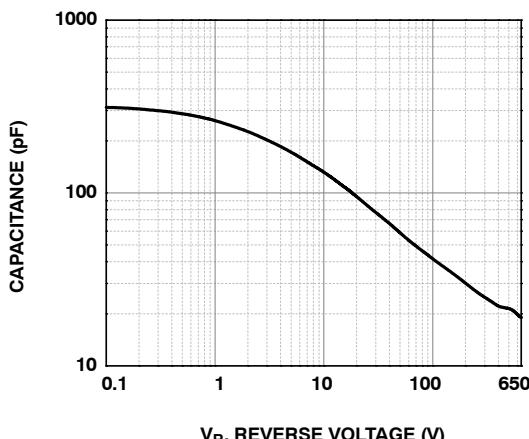


Figure 6. Capacitance vs. Reverse Voltage

TYPICAL CHARACTERISTICS $T_J = 25^\circ\text{C}$ Unless Otherwise Noted (continued)

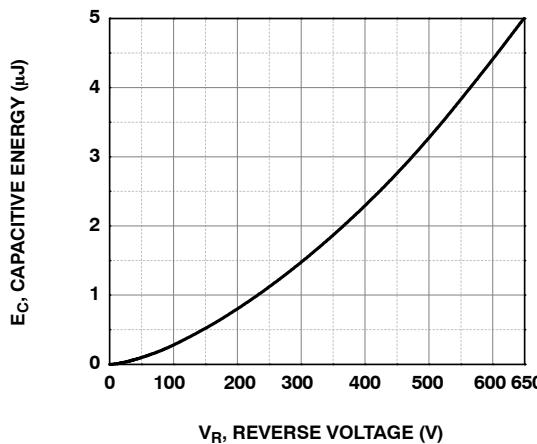


Figure 7. Capacitance Stored Energy

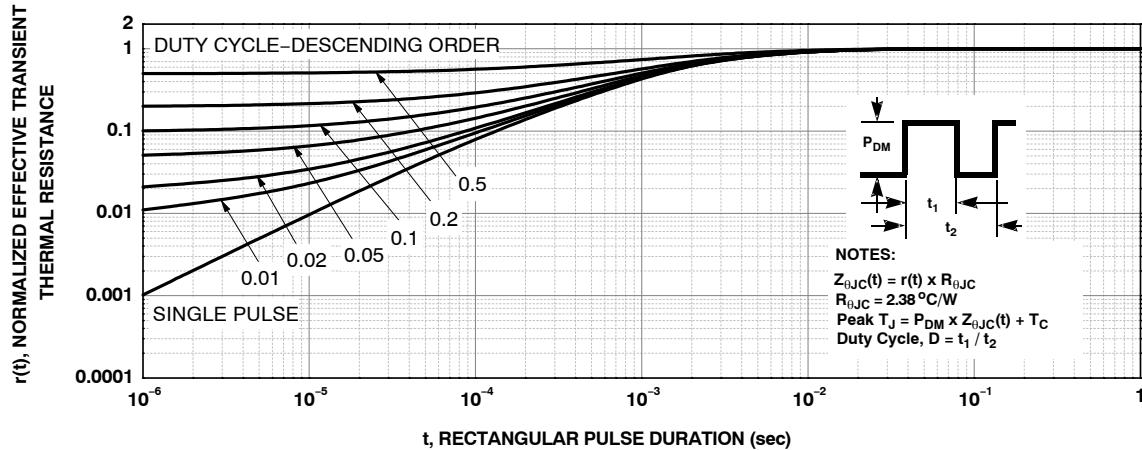


Figure 8. Junction-to-Case Transient Thermal Response Curve

TEST CIRCUIT AND WAVEFORMS

$L = 0.5 \text{ mH}$
 $R < 0.1\Omega$
 $V_{DD} = 50\text{V}$
 $EAVL = 1/2LI^2 [V_{R(AVL)}/(V_{R(AVL)} - V_{DD})]$
 $Q1 = \text{IGBT } (BV_{CES} > \text{DUT } V_{R(AVL)})$

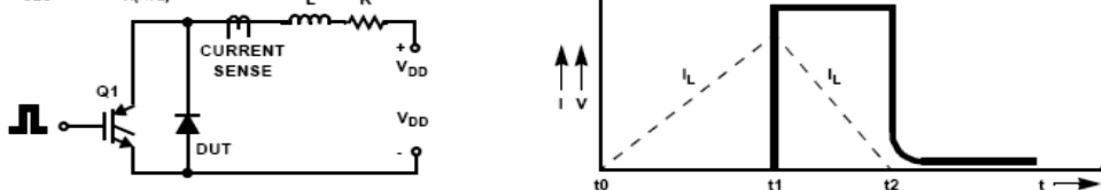
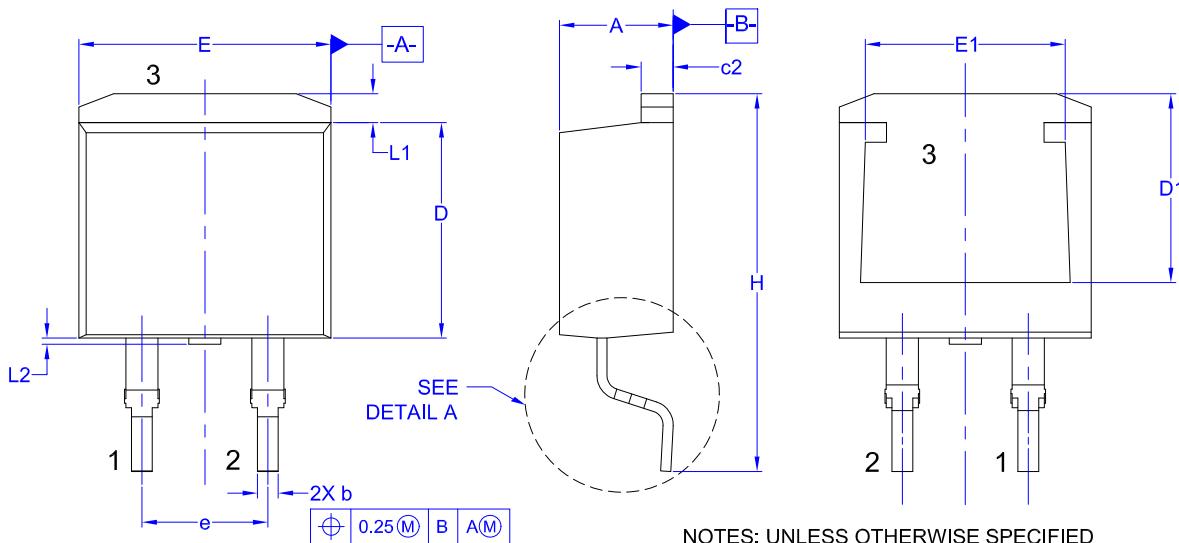


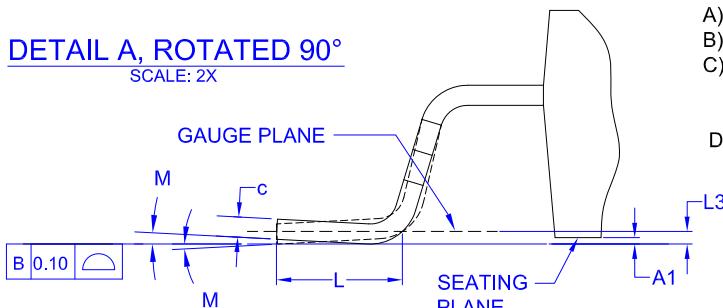
Figure 9. Unclamped Inductive Switching Test Circuit & Waveform

D²PAK2 (TO-263-2L)
CASE 418BK
ISSUE O

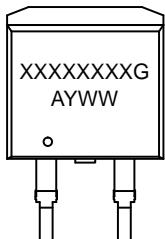
DATE 02 AUG 2018



DETAIL A, ROTATED 90°
SCALE: 2X



**GENERIC
MARKING DIAGRAM***



XXX = Specific Device Code

A = Assembly Location

Y = Year

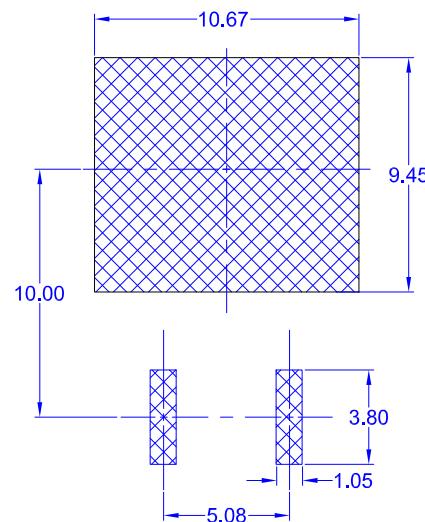
WW = Work Week

G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking.
Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

NOTES: UNLESS OTHERWISE SPECIFIED
A) ALL DIMENSIONS ARE IN MILLIMETERS.
B) REFERENCE JEDEC, TO-263, VARIATION AB.
C) DIMENSIONING AND TOLERANCING PER
DIMENSIONING AND TOLERANCING PER
ASME Y14.5 - 2009.
D) LANDPATTERN RECOMMENDATION PER IPC
TO254P1524X482-3N

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	4.06	4.57	4.83
A1	0.00	0.10	0.25
b	0.51	0.81	0.99
c	0.30	0.407	0.74
c2	1.14	1.30	1.65
D	8.38	8.69	9.65
D1	7.30	7.80	8.30
E	9.65	10.16	10.67
E1	8.00	8.62	9.00
e	5.08 BSC		
H	14.60	15.35	15.88
L	1.78	2.54	2.79
L1	0.90	1.29	1.68
L2	0.00	0.15	0.25
L3	0.25 BSC		
M	0°	4°	8°



LAND PATTERN RECOMMENDATION
UNLESS NOTED, ALL DIMS TYPICAL

DOCUMENT NUMBER:	98AON93788G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	D ² PAK2 (TO-263-2L)	PAGE 1 OF 1

ON Semiconductor and  are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, ONSEMI, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT

North American Technical Support:

Voice Mail: 1 800-282-9855 Toll Free USA/Canada
Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910
For additional information, please contact your local Sales Representative